

WAFER CONNECTOR DIP TYPE

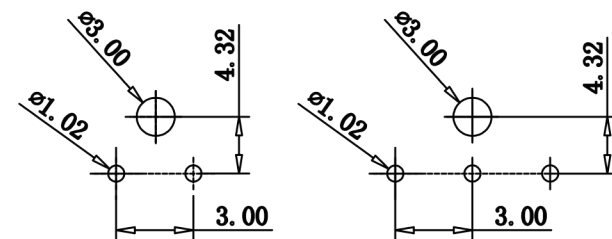
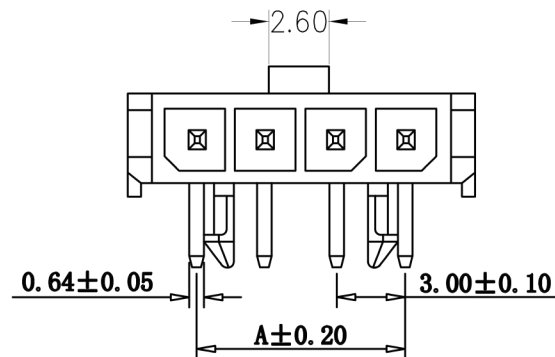
3001 SERIES - 3.00MM



Recommended P.C.B Layout (Top Side)
(PCB BOARD TOLERANCE ±0.05)

Specifications

- Rated current: 5.0AMP
- Voltage rating: 250V AC/DC
- Contact resistance: 20mΩ max
- Withstand Voltage: 1500V AC/minute
- Insulation resistance: 1000MΩ min
- Operation temperature: -40°C to +105°C
- Contact material: Brass
- Contact plating: Tin Over Ni
- Solder Tabs material: Brass/Tin plated
- Insulator material: Polyester (UL94V-0)
- Standard: PA6T
- Max. processing Temp: 230°C for 30-60 seconds
260°C for 10 seconds

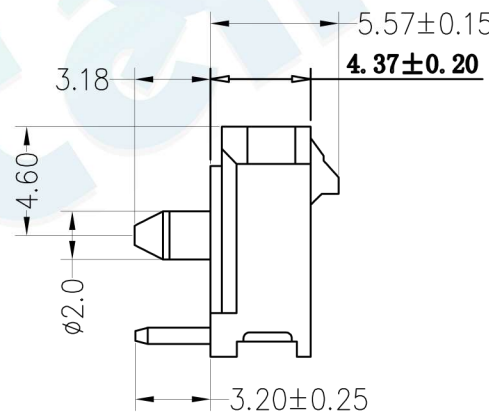
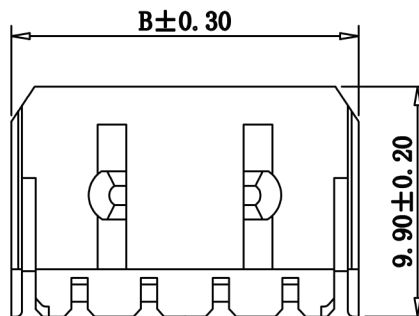
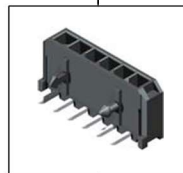


2P
3P
4P-12P

Ordering Information

3001DR1 - (XX) X X (1)

1. Connector Series
2. Number of pins per row (02→12)
3. Insulator Material Option
 - A = BK-PA6T
 - B = BK-PA9T
 - C = BK-LCP
4. Contact plating
 - A = Gold Flash
 - B = Gold Flash/Tin
 - C = Tin
 - D = Matte-Tin

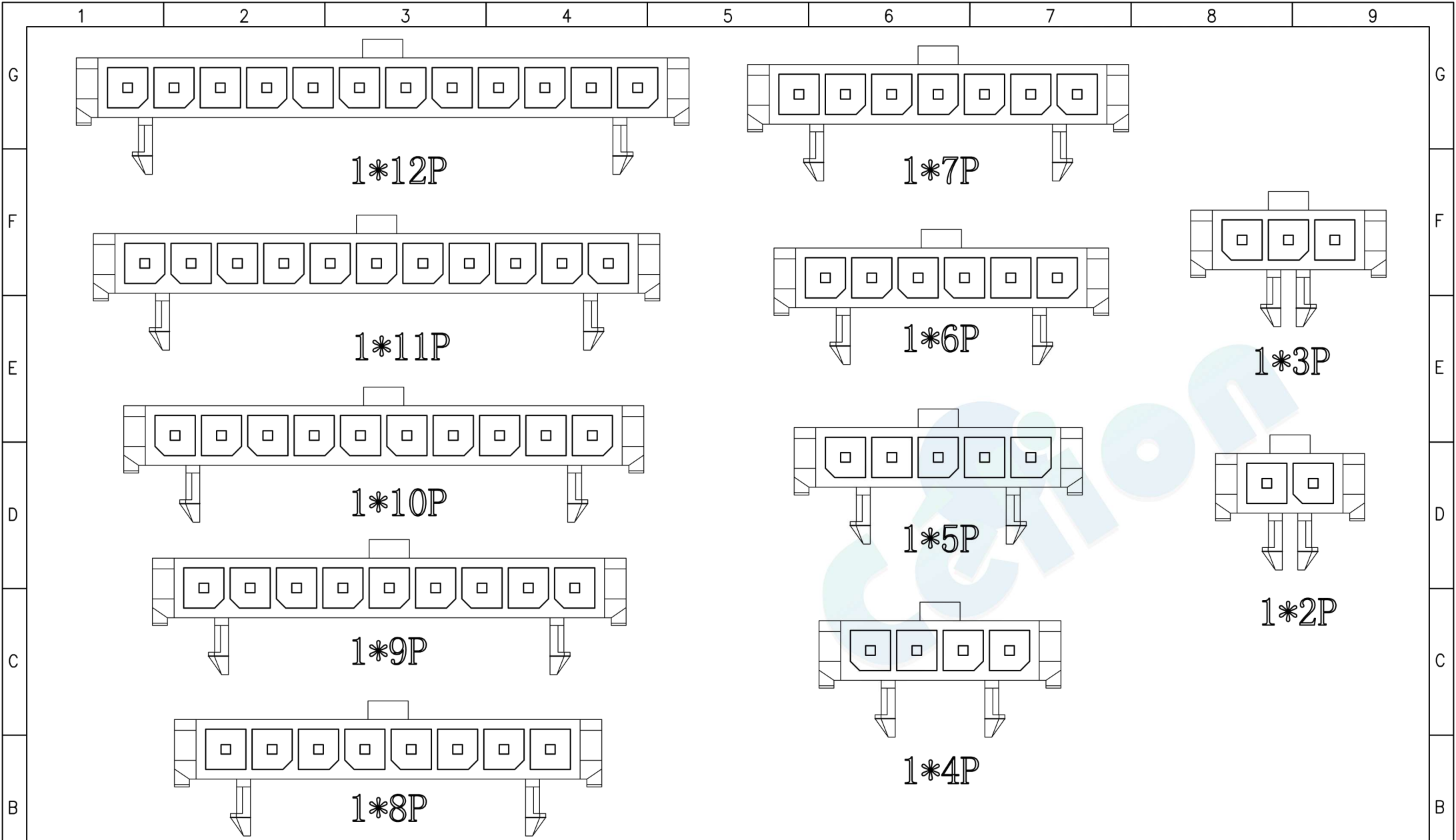




Circuit	Dimension	
	A	B
02	3.00	9.65
03	6.00	12.65
04	9.00	15.65
05	12.00	18.65
06	15.00	21.65
07	18.00	24.65
08	21.00	27.65
09	24.00	30.65
10	27.00	33.65
11	30.00	36.65
12	33.00	39.65

(1). Packaging

Ø=Pe Bag 1=Tube 2=Reel

				OPERATION		DRAW	BEN	12.04.18	SCALE	FIT	 votre partenaire en électronique	
				X.X	±0.30							
				X.XX	±0.20	CHECK			UNIT	mm	PART NO.	3001DR1 - XXXX
				X.XXX	±0.10							
A0	2012.04.18	NEW DRAWING		Angle	±3°	APPROVE			SHEET	1/1	TITLE:	MX3.00mm Wafer Npin 90° DIP
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	DIM							



				OPERATION		DRAW	BEN	12.04.18	SCALE	FIT	 votre partenaire en électronique		
				X.X	±0.30				UNIT	mm			
				X.XX	±0.20	CHECK			SIZE	A4	PART NO.	3001DR1 - XXXX	
				X.XXX	±0.10				SHEET	1/1			
A0	2012.04.18	NEW DRAWING		Angle	±3°	APPROVE			PROJ.		TITLE:	MX3.00mm Wafer Npin 90° DIP	
REV	DATE	MODIFICATION DESCRIPTION		DIM	TOL								